

LEOCO CORPORATION	PRODUCTION SPECIFICATION	No.	S-09-1286-0
* 1286 Series Memory Card Connector *			
This product specification contains the test method; the following datum is the general performance and requirements of the LEOCO 1286 series memory card connector.			
1. Construction and dimensions shall be in accordance with the referenced drawings. 产品结构 and 尺寸依据所提的产品图面			
2. Characteristics 特性: Current rating 额定电流: 0.5 A AC DC Voltage rating 额定电压: 30V AC RMS Temperature rating 额定温度: -20°C ~ +90°C			
3. Electrical performance 电气特性:			
Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 要求
3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method 3004.1 of MIL-STD-1344A.	20 mΩ max. Initial. After test 30 mΩ max.
3-2	Insulation Resistance 绝缘阻抗	In accordance with MIL-STD-202F method 302, DC 500 V shall be applied between contacts and between an individual contact and a case for one minute.	1000 MΩ min initial. After test 1000 MΩ min.
3-3	Dielectric Withstanding Voltage 耐电压	In accordance with MIL-STD-202F method 301, AC 500 V shall be applied between contacts and between an individual contact and a case for one minute. (leak current 2mA)	Neither flashover sparkover nor dielectric breakdown.
4. Mechanical Performance 机械特性 :			
Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 要求
4-1	Terminal Retention Force 端子保持力	Apply axial pull out force at the speed: 25 mm / minute on the terminal assembled is the housing.	3N Min.
4-2	Card Insertion Force 记忆卡插入力	Inserting speed: 25 mm/minute.	40N Max.
4-3	Card Remove Force 记忆卡保持力	Pulling speed of 25 mm/minute.	2N Min.

LEOCO CORPORATION		PRODUCTION SPECIFICATION		No.	S-09-1286-0
5. Environmental Performance 环境特性 :					
Item 项目	Description 内容	Test Method & Condition 测试方法及条件		Requirement 要求	
5-1	Humidity 耐湿性	MIL- STD-1344 A method 1002.2 type I condition B. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 48 hours.		NO damage. Contact resistance less than twice of initial. Insulation resistance more than 50 MΩ	
5-2	Salt Spray 盐雾测试	Connector shall be tested in accordance with method 1001.1 of MIL-STD-1344A condition B. Temperature: 35±2 °C Density: 5 % in weight. Period: 48 hours.		NO damage. Contact resistance less than twice of initial.	
5-3	Solder ability 可焊性	Connector termination ends shall be checked for solder ability in accordance with method 208 of MIL-STD-202F. Solder temperature: 230±5 °C Immersion period: 5±0.5 sec.		NO damage. Minimum: 95 % of immersed area.	
5-4	Resistance soldering heat to	Evaluate under the condition: Soldering pot: 260±5°C, Soldering time: 5±0.5S		NO damage which may affect the performance.	
5-5	Temperature Cycling 冷热冲击测试	Five cycles of the following: a) -55±3 °C 30 minutes b) Normal temperature 10~15 minutes c) 85±3 °C 30 minutes d) Normal temperature 10~15 minutes		NO damage. Contact resistance less than twice of initial.	
APPR BY : Wilson		CHKD BY: Chard		SPEC BY : Topmoon	